Power Converter Systems

Graduate Course EE8407

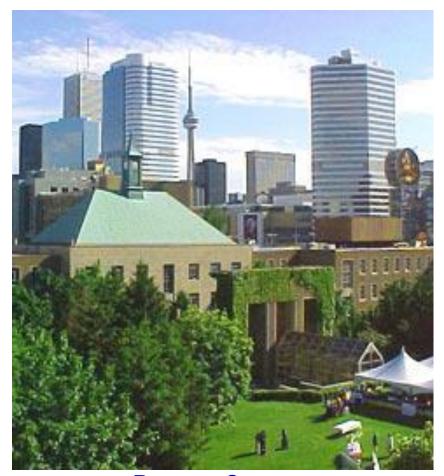
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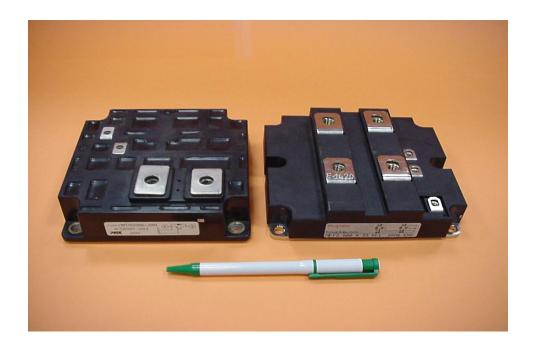
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Ryerson Campus

Topic 2

High-Power Semiconductor Devices



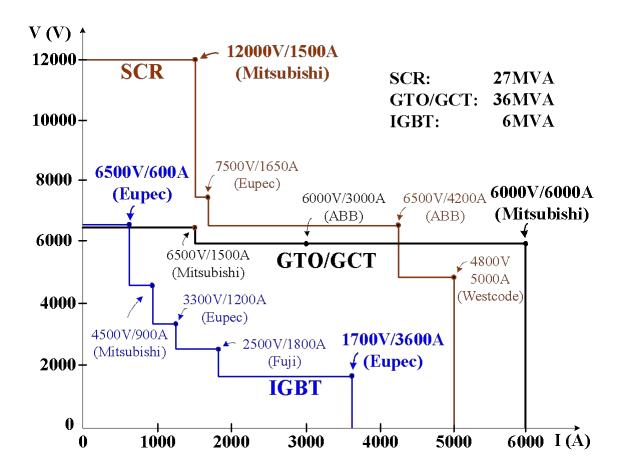
High-Power Semiconductor Devices

Lecture Topics

- Power Diode
- SCR Thyristor
- Gate Turn-Off Thyristor (GTO)
- Integrated Gate Commutated Thyristor (GCT)
- Insulated Gate Bipolar Transistor (IGBT)
- Switch Series Operation

High-Power Semiconductor Devices

Device Rating



EE8407 Topic 2

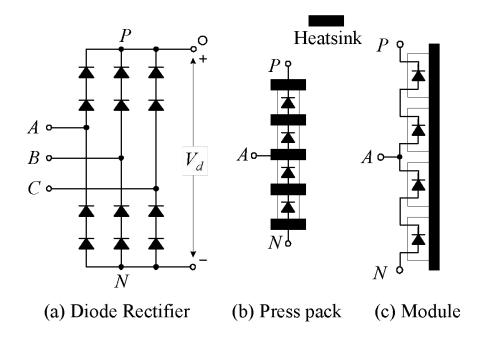
Power Diode



4500V/800A press pack and 1700V/1200A module diodes

Power Diode

Heatsink Assembly



Press pack device:

- Double sided cooling
- Low assembly cost and high power density
- Preferred choice for high voltage high power applications

Topic 2

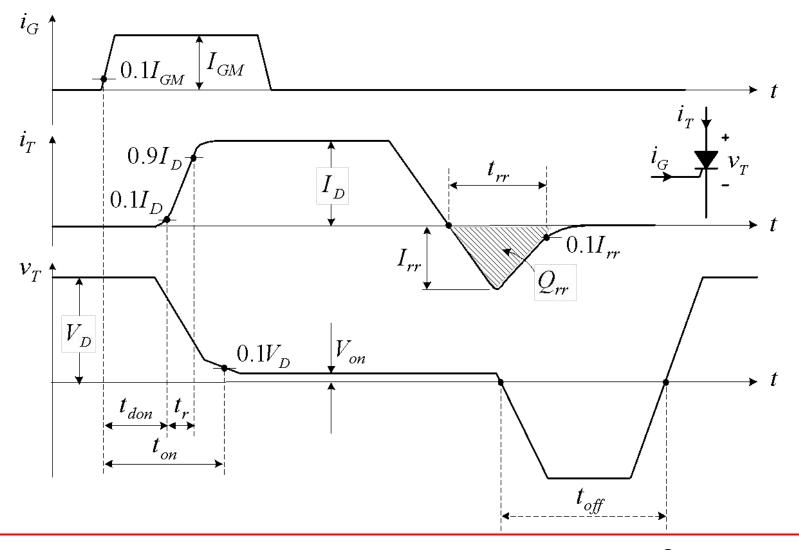
SCR Thyristor



4500V/800A and 4500V/1500A SCRs

SCR Thyristor

Switching Characteristics



SCR Thyristor

Main Specifications

12000V/1500A SCR Thyristor

Maximum	$V_{\it DRM}$	$V_{\it RRM}$	$I_{\it TAVM}$	I_{TRMS}	-
Rating	12000V	12000V	1500A	2360A	-
Switching	<mark>Turn-on</mark> <mark>Time</mark>	Turn-off Time	di _T /dt	dv _T ∕dt	Q_{rr}
Characteristics	$t_{on} = 14 \mu s$	$t_{off} = 1200 \mu s$	$100A/\mu s$	$2000V/\mu s$	7000μC

 $V_{\it DRM}$ – Repetitive peak off-state voltage

 V_{RRM} – Repetitive peak reverse voltage

 $I_{\it RRMS} - {
m Maximum\ rms\ on\text{-}state\ current}$

$$I_{TAVM}$$
 – Maximum average on-state current
$$Q_{rr} = \frac{t_{rr}I_{rr}}{2}$$
 – Reverse recovery Charge

Part number – FT1500AU-240 (Mitsubishi)



4500V/800A and 4500V/1500A GTOs

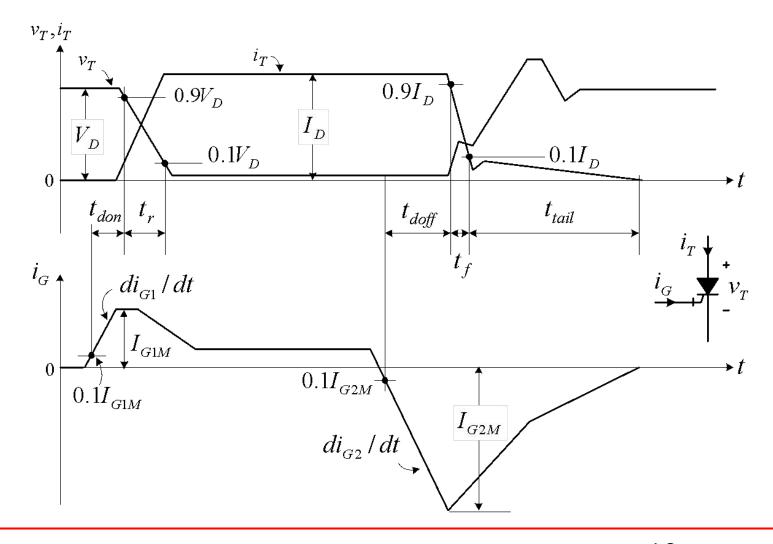
Symmetrical versus Asymmetrical GTOs

Туре	Blocking Voltage	Example (6000V GTOs)	Applications
Asymmetrical GTO	$V_{\it RRM} << V_{\it DRM}$	$V_{DRM} = 6000V$ $V_{RRM} = 22V$	For use in voltage source inverters with anti-parallel diodes.
Symmetrical GTO	$V_{RRM} \approx V_{DRM}$	$V_{DRM} = 6000V$ $V_{RRM} = 6500V$	For use in current source inverters.

 $V_{\it DRM}$ - Maximum repetitive peak (forward) off-state voltage

 $V_{\it RRM}$ - Maximum repetitive peak reverse voltage

Switching Characteristics



Main Specifications

4500V/4000A Asymmetrical GTO Thyristor

Maximum	$V_{\it DRM}$	$V_{\it RRM}$	I_{TGQM}	I _{TAVM}	I _{TRMS}	-
Rating	4500V	17V	4000A	1000A	1570A	-
Switching Characteristics	Turn-on Switching	Turn-off Switching	di _T /dt	dv _T /dt	di _{GI} /dt	di _{G2} /dt
	$t_{don} = 2.5 \mu s$ $t_r = 5.0 \mu s$	$t_{doff} = 25.0 \mu s$ $t_f = 3.0 \mu s$	500A/μs	1000V / μs	40A/μs	40A / μs
On-state Voltage	On-state Voltage $V_{T(on-state)} = 4.4V$ at $I_T = 4000A$					
$V_{\it DRM}$ - Repetitive	oltage	$V_{\it RRM}$ - Repetitive peak reverse voltage				
I_{TGQM} - Repetitive controllable on-state current			$I_{\it TAVM}$ - Maximum average on-state current			
$I_{\it RRMS}$ - Maximum rms on-state current			Part number - 5SGA 40L4501 (ABB)			

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Integrated Gate Commutated Thyristor (GCT)



6500V/1500A Symmetrical GCT

GCT = Improved GTO + Integrated Gate + Anti-parallel Diode (optional)

Integrated Gate Commutated Thyristor

GCT Classifications

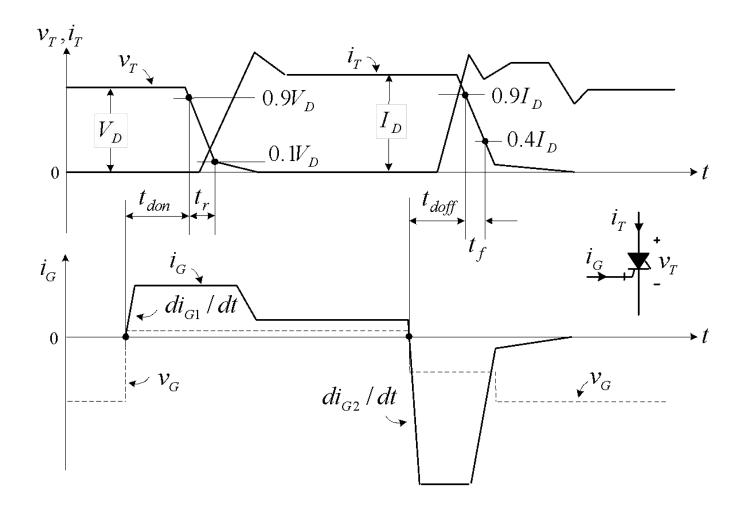
Туре	Anti-parallel Diode	Blocking Voltage	Example (6000V GCT)	Applications
Asymmetrical GCT	Excluded	$V_{\it RRM} << V_{\it DRM}$	$V_{DRM} = 6000V$ $V_{RRM} = 22V$	For use in voltage source inverters with anti-parallel diodes.
Reverse Conducting GCT	Included	$V_{RRM} \approx 0$	$V_{DRM} = 6000V$	For use in voltage source inverters.
Symmetrical GCT (Reverse Blocking)	Not required	$V_{\mathit{RRM}} pprox V_{\mathit{DRM}}$	$V_{DRM} = 6000V$ $V_{RRM} = 6500V$	For use in current source Inverters.

 $V_{\it DRM}$ - Maximum repetitive peak forward off-state voltage

 $V_{\it RRM}$ - Maximum repetitive peak reverse voltage

Integrated Gate Commutated Thyristor

Switching Characteristics



Integrated Gate Commutated Thyristor

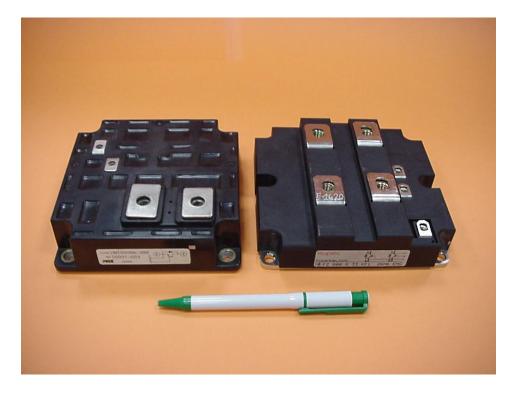
Main Specifications

6000V/6000A Asymmetrical GCT

Maximum	$V_{\it DRM}$	$V_{\it RRM}$	I_{TQRM}	I_{TAVM}	I_{TRMS}	-
Rating	6000V	22V	6000A	2000A	3100A	-
	Turn-on	Turn-off	di₁/dt	dv _T ∕dt	di _{G1} /dt	di _{G2} /dt
Switching	Switching	Switching	1	1	G1	<u> </u>
Characteristics	$t_{don} < 1.0 \mu s$	$t_{doff} < 3.0 \mu s$	$1000A/\mu s$	$3000V/\mu s$	200A / µs	10,000
	$t_r < 2.0 \mu s$	t_f - N/A	100011, 110	, p	200117 pts	$A/\mu s$
On-state	$V_{T(on-state)} < 4V$ at $I_T = 6000A$				•	
Voltage	$T(on-state) \sim T - COOM$					
$V_{\it DRM}$ - Repetitive peak off-state voltage $V_{\it RRM}$ - Repetitive peak reverse voltage						
$I_{\it TGRM}$ - Repetitive controllable on-state current $I_{\it TAVM}$ - Maximum average on-state current					rent	
$I_{\it RRMS}$ - Maximum rms on-state current Part number – FGC6000AX120DS (Mits				itsubishi)		

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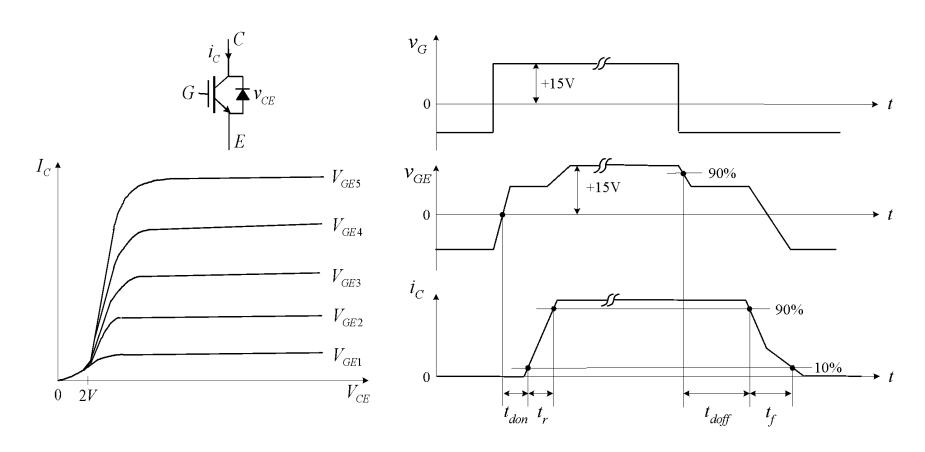
Insulated Gate Bipolar Transistor (IGBT)



1700V/1200A and 3300V/1200A IGBT modules

Insulated Gate Bipolar Transistor (IGBT)

IGBT Characteristics



Static V-I Characteristics

Switching characteristics

Insulated Gate Bipolar Transistor (IGBT)

Main Specifications

3300V/1200A IGBT

Maximum	V_{CE}	I_{C}	I_{CM}	-	
Rating	3300V	1200A	2400A	-	
Switching	t don	t_r	t doff	t_f	
Characteristics	$0.35 \mu s$	$0.27 \mu s$	1.7 μs	$0.2 \mu s$	
Saturation Voltage	$I_{CEsat} = 4.3V$ at $I_C = 1200A$				

 $V_{\it CE}$ - Rated collector-emitter voltage

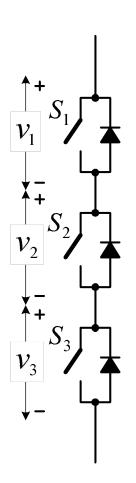
 $I_{\it C}\,$ - Rated dc collector current

 I_{CM} - Maximum repetitive peak collector current

Part number – FZ1200 R33 KF2 (Eupec)

Device Series Operation

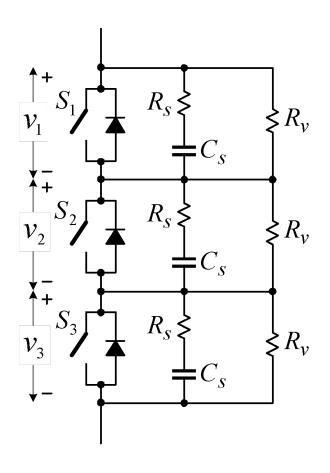
Cause of Voltage Imbalance



Туре	Causes of Voltage Imbalance			
Static Voltage Sharing	$\Delta \! I_{lk}$ — Device off-state leakage current $\Delta \! T_j$ — Junction temperature			
	Device	Δt_{don} — Turn-on delay time Δt_{doff} — Turn-off delay time $\Delta \mathcal{Q}_{rr}$ — Reverse recovery charge of anti-parallel diode ΔT_{j} — Junction temperature		
Dynamic Voltage Sharing	Gate Driver △ – Dif	Δt_{GDon} — Gate driver turn-on delay time Δt_{GDoff} — Gate driver turn-off delay time ΔL_{wire} — Wiring inductance between the the gate driver and the device gate		

Device Series Operation

Equal Voltage Sharing



- S_1 , S_2 , S_3 : GTO, GCT or IGBT
- Voltage Sharing:

$$V_1 = V_2 = V_3$$
 in steady state and transients

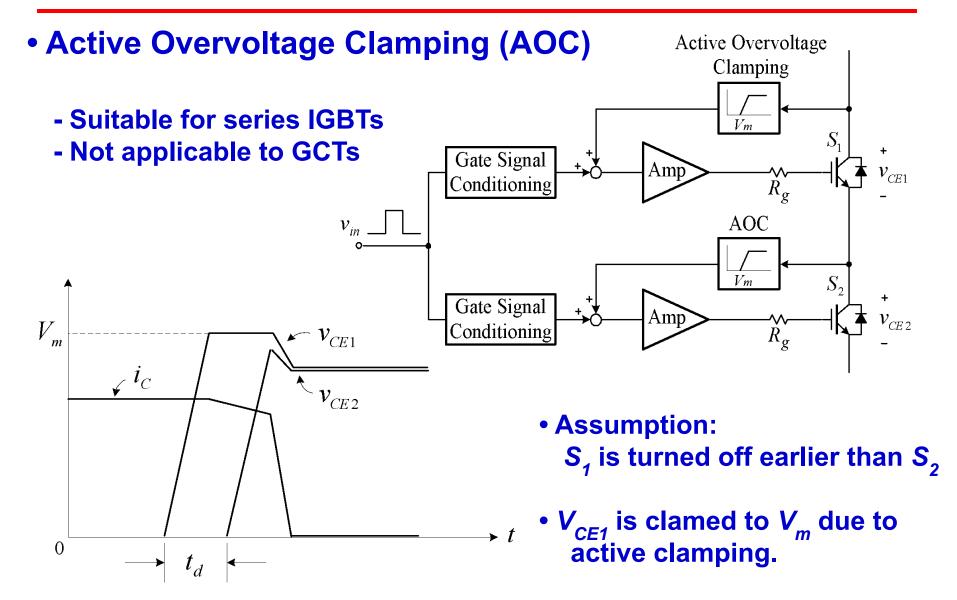
Static Voltage Sharing:

$$R_{v}$$

Dynamic Voltage Sharing:

$$R_s$$
 and C_s

Device Series Operation



Summary

Item	GTO	IGCT	IGBT
Maximum switch power (Device $V \times I$)	36MVA	36MVA	6MVA
Active di/dt and dv/dt control	No	No	Yes
Active short circuit protection	No	No	Yes
Turn-off (dv/dt) snubber	Required	Not required	No required
Turn-on (di/dt) snubber	Required	Required	No required
Parallel connection	No	No	Yes
Switching speed	Slow	Moderate	Fast
Behavior after destruction	Shorted	Shorted	Open in most cases
On-state losses	Low	Low	High
Switching losses	High	Low	Low
Gate Driver	Complex, separate	Complex, integrated	Simple, compact
Gate Driver Power Consumption	High	High	Low

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